

SnBiAg0.4 4-5LT95
No Clean Solder Paste

Product Description

Asahi SnBiAg0.4 4-5LT95 low temperature solder alloy was developed to have better wettability in reflow soldering process. The flux residue is clear, colourless, and provide excellent electrical resistivity.

SnBiAg0.4 4-5LT95 solder paste exhibits long stencil life and tack time, while still delivering exceptional solderability. It possesses excellent printing characteristics to a wide variety of metallization with an anti-slump property.

Application

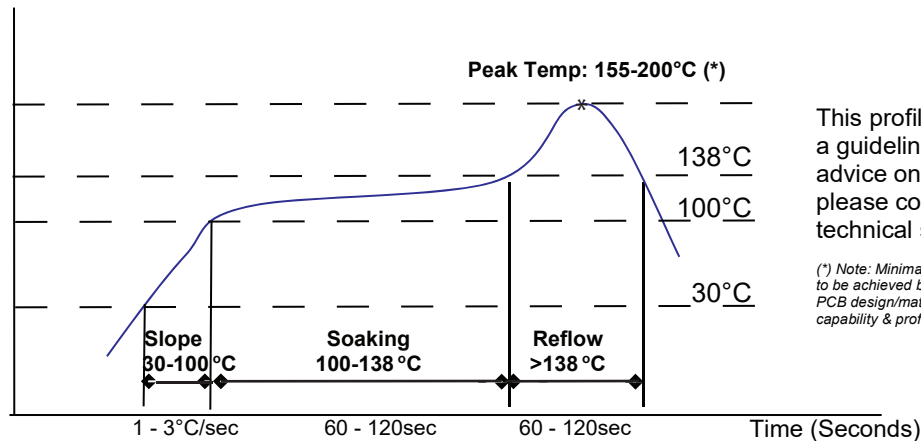
SnBiAg0.4 4-5LT95 is designed for standard stencil printing. The printing speed can be set at 25 - 100 mm/sec. Its optimum printing condition is 23 to 25 °C and humidity of 50 to 65 %RH, with at least 24 hours stencil life of continuous printing (process dependant).

Specification (Preliminary)

Item	Result
Alloy	
Alloy Composition	Sn42/Bi57.6/Ag0.4
Melting Temperature	~138 °C
<small>Differential Scanning Calorimetry</small>	
Powder Size	20 – 38 μm, Type IV,
<small>IPC TM-650 2.2.14</small>	Mesh Size -400 / +635
Paste Flux	
Flux Content	12.0 +/- 1.0 wt%
<small>IPC-TM-650 2.2.20</small>	
Halide Content	Not detected
<small>JIS Z 3197 8.1.4.2.1</small>	
Water Extract Resistivity	> 1 x 10 ⁵ Ω-cm
<small>JIS Z 3197 8.1.1</small>	
Copper Mirror Test	Classified as “L”, Pass
<small>IPC-TM-650 2.3.32</small>	
Flux Activity Classification	ROLO
<small>IPC J-STD-004</small>	
Solder Paste	
Viscosity	400 - 1000 kcPs
<small>IPC-TM-650 2.4.34</small>	
<small>JIS Z 3284 Annex 6</small>	80 - 220 Pa.s
Tackiness	> 100gf
<small>JIS Z 3284 Annex 9</small>	
Surface Insulation Resistance	> 1 x 10 ⁸ Ω, Pass
<small>(85°C, 85%RH, 168hrs)</small>	
<small>IPC-TM-650 2.6.3.3</small>	
Electromigration	Pass
<small>(85°C, 88.5%RH, 596hrs)</small>	
<small>IPC-TM-650 2.6.14.1</small>	
Slump Test	Pass
<small>JIS Z 3284 Annex 7, Annex 8</small>	
Solder Ball Test	Pass
<small>IPC-TM-650 2.4.43</small>	
<small>JIS Z 3284 Annex 11</small>	

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Recommended Reflow Profile



This profile is simply a guideline. For more advice on profiling, please contact Asahi technical support.

(* Note: Minimal peak temperature to be achieved but is dependent on PCB design/material and process capability & profiling in accuracy.

Residue Removal

Residue removal is not needed as this is a no clean solder paste. For assemblies that require cleaning, call Asahi technical support.

Storage, Handling and Shelf Life

Solder paste has to be thawed to room temperature (~25°C) prior using to avoid condensation. Paste left on the stencil should not be put back into the container together with the unused paste. It is preferable not to re-use solder paste left on the stencil after printing.

Generally the solder paste could last for 6 months from date of manufacturing, if kept under proper condition and temperature of 0 - 10 °C.

Health and Safety

Do not handle the paste with your bare hand. Use proper tool when handling the paste. If the paste touches the skin, wash thoroughly with soap and water. For more information, please refer to Material Safety Data Sheet.

Packaging

Packaging Type	Weight	Packaging Part
Jar	500g	E
	250g	F
Cartridge	1000g	D
Cassette	800g	I
Easipak	150g	J
	50g	H

Solder Paste Product Order System:

Alloy Type Powder Size - Formula Type - Packaging Part

Example: SnBiAg0.4 4-5LT95-E

DISCLAIMER OF LIABILITY

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Singapore Asahi Chemical and Solder Industries Pte Ltd

47 Pandan Road Singapore 609288

Tel: +65 6262-1616 Fax: +65 6261-6311

Website: <http://www.asahisolder.com> Email: enquiry@sinasahi.com.sg